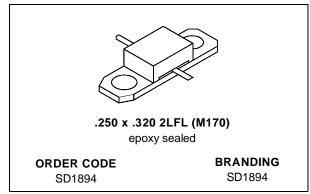




RF & MICROWAVE TRANSISTORS SATELLITE COMMUNICATIONS APPLICATIONS

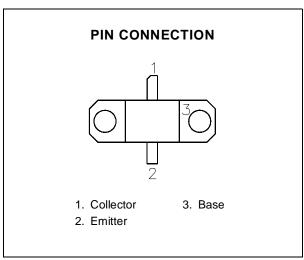
- CLASS C
- 1.6 GHz
- COMMON BASE
- REFRACTORY/GOLD METALLIZATION
- EFFICIENCY = 50% MIN.
- P_{OUT} = 4.5 W MIN. WITH 10 dB GAIN



DESCRIPTION

The SD1894 is a common base silicon NPN bipolar device optimized for 1.6 GHz SATCOM applications.

The SD1894 offers superior gain and collector efficiency, making it an ideal choice for Class C power amplifiers used in portable as well as fixed SAT-COM terminals.



ABSOLUTE MAXIMUM RATINGS $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage	45	V
Vces	Collector-Emitter Voltage	45	V
V _{EBO}	Emitter-Base Voltage	3.0	V
Ic	Device Current	375	mA
P _{DISS}	Power Dissipation	12.5	W
TJ	Junction Temperature	+200	°C
T _{STG}	Storage Temperature	- 65 to +150	°C

THERMAL DATA

R _{TH(j-c)} Junction-Case Thermal Resistance 14.0 °C/W

February 4, 1997

ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)

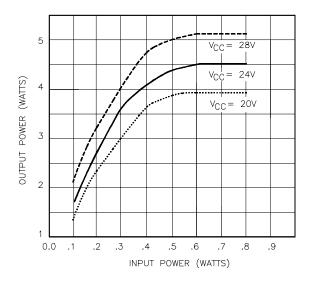
STATIC

Symbol	Test Conditions		Value			Unit	
Syllibol			Min.	Тур.	Max.	Oiii	
BV _{CBO}	I _C = 1 mA	$I_E = 0 \text{ mA}$		45		l	V
BVces	I _C = 1 mA	$V_{BE} = 0 V$		45	_		V
BV _{EBO}	$I_E = 1 \text{ mA}$	$I_C = 0 \text{ mA}$		3.0		1	V
I _{CBO}	V _{CB} = 28 V	$I_E = 0 \text{ mA}$		_	_	.25	mA
h _{FE}	V _{CE} = 5 V	$I_C = .2 A$		15	_	150	_

DYNAMIC

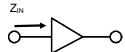
Symbol	Test Conditions			Value			Unit
Symbol				Min.	Тур.	Max.	Oilit
P _{IN}	f = 1650 MHz	V _{CC} = 28 V	P _{OUT} = 4.5 W		.35	.45	W
ης	f = 1650 MHz	V _{CC} = 28 V	P _{OUT} = 4.5 W	50	55	_	%
Pg	f = 1650 MHz	V _{CC} = 28 V	P _{OUT} = 4.5 W	10.0	11.1	_	dB
Load Mismatch	V _{CC} = 28 V	$P_{OUT} = 4.5 \text{ W}$	VSWR = 20:1	No Degradation in Output Power			า

INPUT POWER vs OUTPUT POWER

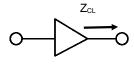


IMPEDANCE DATA



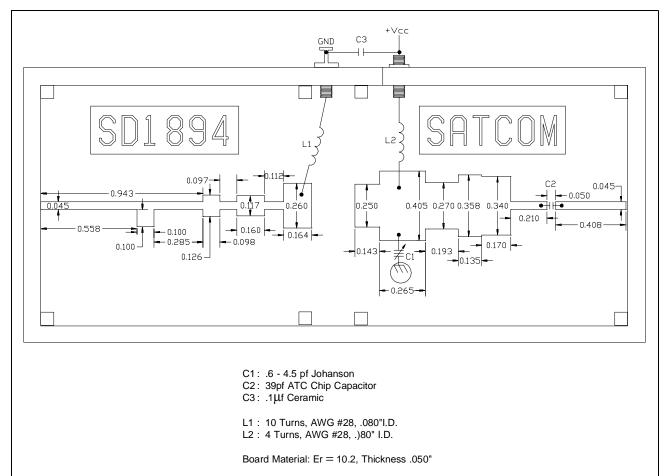


TYPICAL COLLECTOR LOAD IMPEDANCE



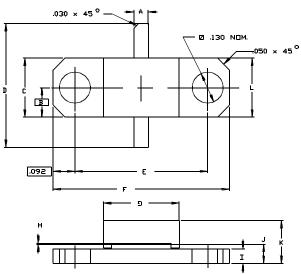
FREQ.	Z _{IN} (Ω)	Z _{CL} (Ω)
1600 MHz	31.6 + j 21.4	5.2 + j 14.7
1620 MHz	38.0 + j 15.0	5.6 + j 14.55
1635 MHz	38.8 + j 11.3	5.85 + j 14.45
1650 MHz	36.0 + j 9.1	6.1 + j 14.3
1665 MHz	34.3 + j 8.77	6.37 + j 14.2

TEST CIRCUIT



PACKAGE MECHANICAL DATA

Ref.: Dwg. No.12-0170 UDCS No. 1010996 rev B



SGS-THOMSON MICROELECTRONICS				CONT'D		
	M[NIMUM Inches/mm	MAXIMUM]nches/mm		M[N]MUM]nches/nm	MAXIMUM Inches/mm	
Α	.055/1,40	.065/L65	к		.190/4,83	
В	.124/3,15		L	.245/6,22	.255/6,48	
С	.243/6,17	.253/6,43				
D	.635/16,13	.665/16,89				
E	.555/14,10	.565/14,35				
F	.739/18,77	.749/19,02				
G	.315/8,00	.325/8,26				
н	.002/0,05	.006/0,15				
I	.055/1,40	.065/1,65				
J	.075/1,91	.095/2,41				

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